

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Kuo-Yu Chou **EXAMINER:**

Le, Thao X.

SERIAL NO.:

10/043,709

ART UNIT:

2814

FILED:

01/09/2002

ATTY DKT NO.: 67,200-603

TITLED: A SINGLE LAYER WIRING BOND PAD WITH OPTIMUM AL FILM THICKNESS

IN CU/FSG PROCESS FOR DEVICES UNDER PADS

CERTIFICATE OF MAILING

Please forward all correspondence to:

TUNG & ASSOCIATES Suite 120 838 W. Long Lake Road Bloomfield Hills, MI 48302 I hereby certify that this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450

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Alexandria, VA 22313-1450

RESPONSE UNDER 37 C.F.R. §1.111

Dear Sir:

In response to the Office Action dated August 13, 2003 (Paper No. 9) in the above captioned matter, please enter the following remarks:

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